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# **DMG20102**

## Silicon NPN epitaxial planar type (Tr1) Silicon PNP epitaxial planar type (Tr2)

## For general amplification

#### ■ Features

- $\bullet$  High forward current transfer ratio  $h_{\text{FE}}$  with excellent linearity
- ullet Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Halogen-free / RoHS compliant
   (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

## ■ Marking Symbol: CY

#### ■ Basic Part Number

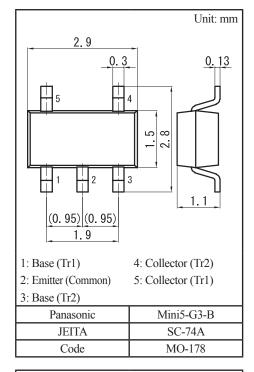
DSC2002 + DSA2002 (Common emitter)

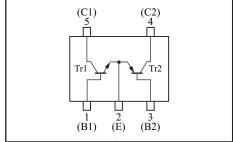
#### Packaging

DMG201020R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	V <sub>CBO</sub>	60	V
	Collector-emitter voltage (Base open)	V <sub>CEO</sub>	50	V
	Emitter-base voltage (Collector open)	V <sub>EBO</sub>	5	V
	Collector current	$I_{C}$	500	mA
	Peak collector current	$I_{CP}$	1	A
Tr2	Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-60	V
	Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-50	V
	Emitter-base voltage (Collector open)	$V_{\mathrm{EBO}}$	-5	V
	Collector current	$I_{C}$	-500	mA
	Peak collector current	$I_{CP}$	-1	A
Overall	Total power dissipation	$P_{T}$	300	mW
	Junction temperature	$T_{j}$	150	°C
	Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C
	Storage temperature	T <sub>stg</sub>	-55 to +150	°C





## ■ Electrical Characteristics $T_a = 25$ °C±3°C

#### • Tr1

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = 10 \mu A, I_E = 0$	60			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Emitter-base voltage (Collector open)	$V_{\mathrm{EBO}}$	$I_E = 10 \mu A, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Farment transfer action	h <sub>FE1</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$	120		340	
Forward current transfer ratio	h <sub>FE2</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 500 \text{ mA}$	40			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.1	0.6	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_{C} = 50 \text{ mA}$		160		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		4.8	15	pF

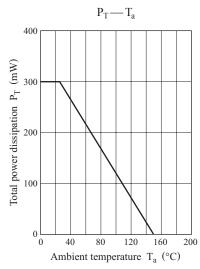
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

#### • Tr2

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = -10  \mu \text{A}, I_{\rm E} = 0$	-60			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \mu A, I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{\rm CB} = -20 \text{ V}, I_{\rm E} = 0$			-0.1	μΑ
Forward current transfer ratio	h <sub>FE1</sub>	$V_{CE} = -10 \text{ V}, I_{C} = -150 \text{ mA}$	120		340	
Forward current transfer ratio	h <sub>FE2</sub>	$V_{CE} = -10 \text{ V}, I_{C} = -500 \text{ mA}$	40			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -300 \text{ mA}, I_B = -30 \text{ mA}$		-0.2	-0.6	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = -300 \text{ mA}, I_B = -30 \text{ mA}$		- 0.9	-1.5	V
Transition frequency	$f_T$	$V_{CE} = -10 \text{ V}, I_{C} = -50 \text{ mA}$		130		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		7.3	15	pF

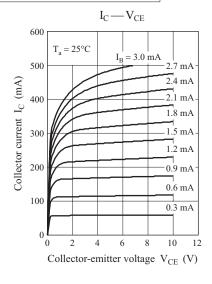
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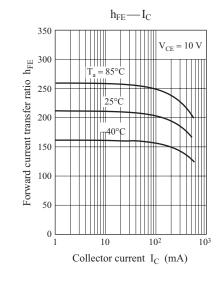
## Common characteristics chart

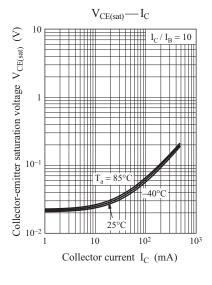


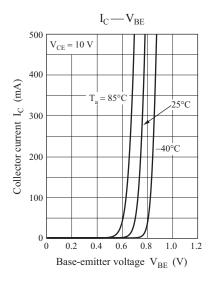
Ver. DED 2

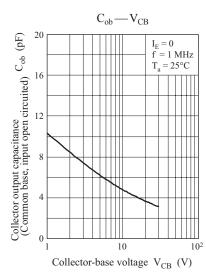
## Characteristics charts of Tr1

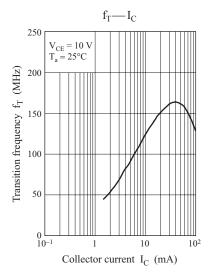




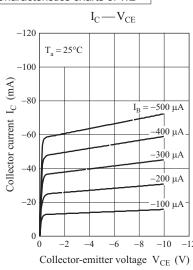


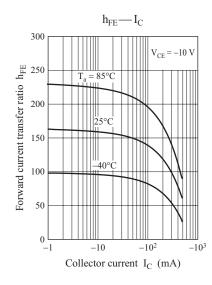


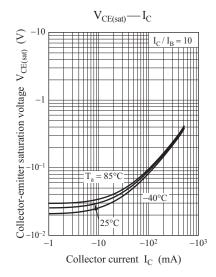




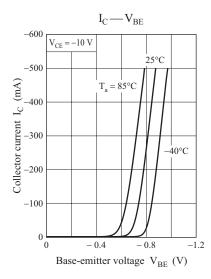
#### Characteristics charts of Tr2

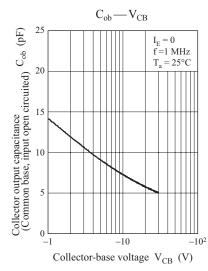


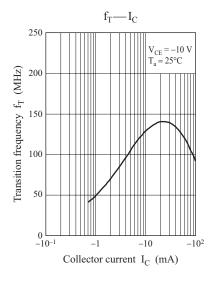




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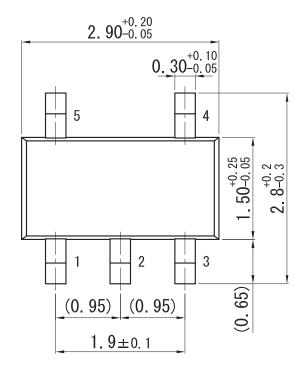


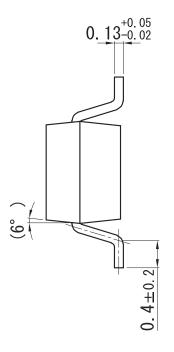


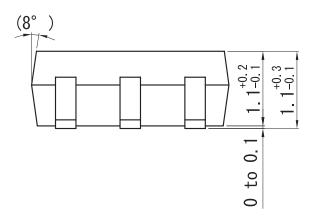
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Mini5-G3-B

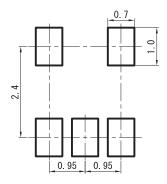
Unit: mm







## ■ Land Pattern (Reference) (Unit: mm)



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